

LEC-BASE R1

SMARC Reference Carrier Board

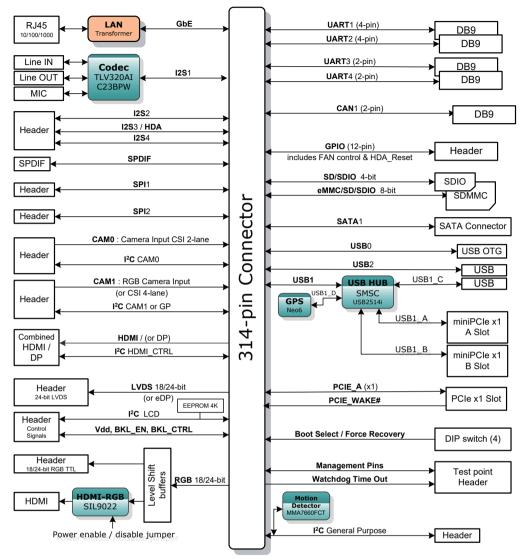
Features

- SMARC compliant carrier board with MXM3 connector
- Compatible with both short and full size SMARC modules
- Supports parallel RGB, LVDS and HDMI displays
- Two mini PCIe slots for expansion cards (e.g. Wi, 3G, ...) (not included) and two SIM card slots
- 2 camera connectors
- 4x UART, 2x CAN
- USB hub

Specifications

Interfaces		PCI Express	One PCIe x1 link connector Two mini PCIe x1 slots	
Display	Combined HDMI, DP LVDS 18/24-bit or eDP Panel support signals (I2C, Power Enables, PWM) Combined HDMI, 18/24-bit RGB		PCIe Gen1 or Gen 2 (module dependent) Reference clock pair Full set of PCIe support signals PCIe wake signal	
Camera	Camera input 0: CSI-2 Camera input 1: RGB or CSI-4	SATA Ethernet	One SATA with power interface RJ-45 10/100/1000 Ethernet (by LAN transformer)	
SDIO	4-bit SD/SDIO card interfaces 8-bit eMMC/SD/SDIO interfaces	S/PDIF Boot Select Jumpers	S/PDIF header for audio Module: SPI/eMMC/NOR/NAND	
SPI	Off module boot use (optional) G-sensor ADXL345 BCCZ	CDIO	Carrier: SPI/eMMC/SD Card/SATA DIP Switch (4)	
l²S	2x SPI interface 3x I²S interface - Audio codec TLV320AIC23BPW - Line-in, Line-out, Mic - Optional with HDA	GPIO Alternate Function Blocks	12-pin header (including fan control and HDA reset) Dedicated AFB connector Pinout is module dependent (see SMARC specication)	
I ² C	- Optional with HDA 4x I ² C - Power Management	Mechanical and	echanical and Environmental	
	- HDMI - Camera 0 - Camera 1 or GP	Dimension Board Connector	330 mm x 175 mm (L x W) MXM 314 pins	
Asynchronous Serial Port	4x asynchronous serial ports (UART) - Two with 2 wire handshake (RXD, TXD, RTS#, CTS#) - Two with data only (RXD, TXD)	Ordering I	Information	
CAN Bus	- Logic level interface 2x CAN bus (D-SUB9) Logic level signals from module based CAN bus protocol controllers	LEC-BASE-R01 2SMARC Refer 330 x 175 mm	ence Carrier Board, MXM 314 pins,	
USB	RXD, TXD only 5x USB - One with USB 2.0 OTG - 4x USB 2.0 Host operation (full speed and high speed)	*other configuratic	ons by request	

Functional Diagram



Intelligent Middleware



Middleware Name	SEMA®
Description	Local management, control of embedded
	computer systems
	Extended EAPI for monitoring, controlling and
	analytics applications
	Multiple OS support and across platforms
	(x86, ARM)

Intelligent IOT Platform



Platform Name	SEMA Cloud®
Description	Application ready comprehensive industrial grade IoT Platform
	Connecting Devices to a Cloud Platform and to
	Web Applications
	Remote monitoring and controlling managing of connected devices
	Enabling integration of operational device data into business processes
	Cloud based Platform as a Service (PaaS)



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